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KM PTO-1449 (SUBSTITUTE)

U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE

INFORMATION DISCLOSURE STATEMENT BY APPLICANT (37 CFR 1.98(b))

Attorr	ney D	ocket l	No.:
GR 9	98 P	4137	Р

Applic. No.

09/761,594

Applicant

Hans-Jürgen Hacke et al.

Filing Date

Group Art Unit

January 16, 2001

U.S. PATENT DOCUMENTS

EXAMINER INITIALS		PATENT NO.	DATE	PATENTEE	CLASS	SUB CLASS	FILING DATE
194	Α	4,922,321	05/01/90	Arai et al.			
OTU	В	5,074,947	12/24/91	Estes et al.			
oru	С	5,477,087	12/19/95	Kawakita et al.	_		-
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FOREIGN PATENT DOCUMENT

		DOCUMENT NO.	DATE	COUNTRY	CLASS	CLASS		NSL. JNO
11/10	J _	-0·734 059 A2	09/25/96	European			X	
114	Κ.	05 062 981	03/12/93	Japan			X	
OFM	L	06 232 134	08/19/94	Japan			X	
	М							
	N							

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, etc.)

AM	0	International Publication WO 96/22620 (Pedersen et al.), dated July 25, 1996
PRI	Р	Shinji Baba et al.: "Molded Chip Scale package for High Pin Count", 1996 Electronic Components and Technology Conference, pp. 1251-1257, XP-000684987

EXAMINER DATE CONSIDERED

EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

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"Solder Plated Resin Ball", IBM Technical Disclosure Bulletin, pp. 463-464

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